



PRODUCT BULLETIN # 20247

Issue Date: 16-Oct-2013

TITLE: Change Unit Probe to Sample Probe

PROPOSED FIRST SHIP DATE: 16-Oct-2013

AFFECTED CHANGE CATEGORY(S): Standard Product Group (SPG)

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:

Contact your local ON Semiconductor sales office or <MohdHezri.AbuBakar@onsemi.com>

NOTIFICATION TYPE:

ON Semiconductor considers this change approved unless specific conditions of acceptance are provided in writing. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

On Semiconductor is doing a change on wafer probe measurement from unit probe to sample probe for some TMOS7 devices to maximize the probe capacity.

Final test at post-assembly device level has extensive coverage compared to probe test. Sample probe is good enough to check the dice on wafer level are functional and meeting critical electrical parameters. Changing from unit probe to sample probe does not degrade the test quality and defects detection capability that we have for end products.

**PRODUCT BULLETIN #20247****List of affected Standard Parts:**

NTB25P06T4G
NTB45N06T4G
NTB5605PT4G
NTBV45N06T4G
NTBV5605T4G
NTC3055L104WP
NTD18N06LT4G
NTD20N06T4G
NTD20P06LG
NTD20P06LT4G
NTD2955-1G
NTD2955G
NTD2955T4G
NTD3055L104-1G
NTD3055L104G
NTD3055L104T4G
NTDV20P06LT4G
NTDV3055L104T4G
NTF2955T1G
NTF3055L108T1G
NTP2955G
NVB25P06T4G
NVD2955T4G
NVF2955T1G
NVF3055L108T1G
NVF3055L108T3G